

DEVICE PROCESS FLOW OPTIONS

The following table indicates the standard Eltek device processing options. Additional testing and screening options are available, please contact Eltek with your requirements.

SCREENING	Method	Commercial flow	Extended temperature flow	Extended temperature + burn-in flow	Eltek mil-aero flow (1)	Customer SCD flow
Device suffix		/C	/M1	/M2	/M3	/M4
Die shear test	2019	Y	Y	Y	Y	@
Bond strength	2011	Y	Y	Y	Y	@
Internal visual	2010	N	S	S	Y	@
QC lot acceptance	2010	S	S	S	Y	@
Stabilisation bake	1008	Y	Y	Y	Y	@
Temperature cycling	1010	N	N	N	Y	@
Constant acceleration	2001	N	N	N	Y	@
Fine leak test	1014	N	Y	Y	Y	@
Gross leak test	1014	N	Y	Y	Y	@
Interim electrical @25 C	#	N	N	Y	Y	@
Burn-in, 160 hours @125 C	1015	N	N	Y	Y	@
Final electrical @25 C	#	Y	Y	Y	Y	@
Final electrical at T.max / T.min	#	N	Y*	Y*	Y	@
External visual	2009	Y	Y	Y	Y	@

S = Eltek in-house process control sample

= Per applicable datasheet

* = Temperature range defined by device specification

@ = Performed to customer requirements

Note 1 : Eltek military flow follows the screening procedures defined in method 5004 of MIL-STD-883, Eltek does not claim compliance with paragraph 1.2.1 of MIL-STD-883.

For MIL-STD-883, class S requirements, please contact Eltek.